



Silicon Wafer Japan TC Chapter

Japan Standards Summer 2023 Meetings

Friday, August 25, 2023

SEMI Japan office, Tokyo, Japan / WEB(Hybrid)

To be conducted by Official Virtual TC Chapter Meeting

<10:00 –noon JST>

AGENDA

	Time
1 Welcome/Call to Order	10:00
1.1 Introductions	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Agenda Review	
2 Review of Previous Meeting Minutes	
3 Ballot Review	
None	
4 Subcommittee & Task Force Reports	
4.1 International Advanced Wafer Geometry TF	
4.2 International / Japan Test Method TF	
4.3 International Advanced Surface Inspection TF	
4.4 International Polished Wafers TF	
4.5 International Epitaxial Wafers TF	
4.6 International Annealed Wafers TF	
4.7 International SOI Wafers TF	
4.8 International Terminology TF	
5 Liaison Report	
5.1 Europe TC Chapter	
5.2 North America TC Chapter	
5.3 GCS Report	
6 Staff Report	

7 Old Business

7.1 Project Period Review

7.2 5 Year Review Check

7.2.1 SEMI M51-1012: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity

7.2.2 SEMI M60-1014: Test Method for Time Dependent Dielectric Breakdown Characteristics of SiO₂ Films for Si Wafer Evaluation

8 New Business

8.1 Proposal of New Activity

9 Action Item Review

9.1 Open Action Items

9.2 New Action Items

10 Next Meeting and Adjournment

12:00

10.1 The next meeting is scheduled for <date> at <event/location>.